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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :

Juen-Kuen LIN, et al.

: EXAMINER: NGUYEN, D

SERIAL NO: 09/741,072

:

RCE FILED: Herewith

: GROUP ART UNIT: 3723

FOR: WAFER POLISHING HEAD

RECEIVED  
SEP 20 2001  
TC 3750 MAIL ROOM

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the official Office Action dated April 18, 2001, and the Advisory Action dated July 20, 2001, which denied the entry of the Amendment filed July 18, 2001, please amend the above-identified patent application as follows:

IN THE CLAIMS

Please amend Claims 1 and 7 as shown in the attachment. A clean copy of the claims incorporating any amendment is shown below.

- 91
- 1. (Amended) A wafer polishing head for planarizing a wafer, comprising:
- a carrier for loading the wafer;
  - a wafer adhering layer disposed beneath the carrier;
  - a retaining ring surrounding the carrier and the wafer adhering layer;